# MOSFET – Power, N-Channel, SUPERFET<sup>®</sup> III, Easy Drive

# **650 V, 44 A, 67 m**Ω

#### Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET Easy drive series helps manage EMI issues and allows for easier design implementation.

#### Features

- 700 V @ T<sub>J</sub> = 150°C
- Typ.  $R_{DS(on)} = 59 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 78 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 715 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

#### Applications

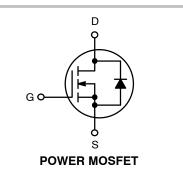
- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar

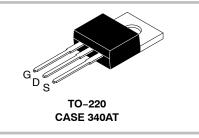


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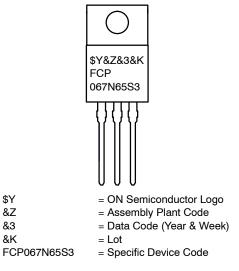
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V <sub>DSS</sub> R <sub>DS(ON)</sub> MA		I <sub>D</sub> MAX
650 V	$67~\mathrm{m}\Omega$ @ 10 V	44 A





#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	FCP067N65S3	Unit V	
V <sub>DSS</sub>	Drain to Source Voltage			650
V <sub>GSS</sub>	Gate to Source Voltage	– DC	±30	V
		– AC (f > 1 Hz)	±30	
۱ <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C)	44	А
		– Continuous (T <sub>C</sub> = 100°C)	28	
I <sub>DM</sub>	Drain Current	Prain Current - Pulsed (Note 1)		А
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		214	mJ
I <sub>AS</sub>	Avalanche Current (Note 2)		4.8	А
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		3.12	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C)	312	W
		- Derate Above 25°C	2.5	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse width limited by maximum junction temperature. 2.  $I_{AS} = 4.8 \text{ A}, V_{DD} = 50 \text{ V}, R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \leq 22 \text{ A}, \text{ di/dt} \leq 200 \text{ A/}\mu\text{s}, V_{DD} \leq 380 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$ .

#### **THERMAL CHARACTERISTICS**

Symbol	Parameter	FCP067N65S3	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.4	°C/W
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP067N65S3	FCP067N65S3	TO-220	Tube	N/A	N/A	50 Units

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACT	ERISTICS	-			•	
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA, $T_J$ = 25°C	650	-	-	V
		$V_{GS}$ = 0 V, $I_{D}$ = 1 mA, $T_{J}$ = 150°C	700	-	-	V
$\Delta \text{BV}_{\text{DSS}}  /  \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 1$ mA, Referenced to 25°C	-	0.72	_	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 650 V, $V_{GS}$ = 0 V	-	-	1	μΑ
		$V_{DS}$ = 520 V, $T_{C}$ = 125°C	-	2.2	-	
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS}=\pm30~\text{V},~\text{V}_{DS}=0~\text{V}$	-	-	±100	nA
ON CHARACTE	RISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 1.0$ mA	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 22 \text{ A}$	-	59	67	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 22 \text{ A}$	-	29	-	S
DYNAMIC CHAI	RACTERISTICS			•		
C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 400 V, $V_{GS}$ = 0 V, f = 1 MHz	-	3090	-	pF
Coss	Output Capacitance	-	-	68	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$	-	715	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS} = 0 \text{ V}$ to 400 V, $V_{GS} = 0 \text{ V}$	-	104	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 22 A, V <sub>GS</sub> = 10 V (Note 4)	-	78	-	nC
Q <sub>gs</sub>	Gate to Source Gate Charge		-	18	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	30	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.6	-	Ω
WITCHING CH	IARACTERISTICS	-			•	
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 22 \text{ A}, \text{ V}_{GS} = 10 \text{ V},$	-	26	-	ns
t <sub>r</sub>	Turn-On Rise Time	R <sub>g</sub> = 4.7 Ω (Note 4)		52	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	1`´´		89	-	ns
t <sub>f</sub>	Turn-Off Fall Time	1	-	16	-	ns
SOURCE-DRAI	N DIODE CHARACTERISTICS	•		•	•	•
۱ <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current			-	44	Α
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current		-	-	110	Α
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_{SD} = 22 A$	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 22 A,$	-	435	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> /dt = 100 A/μs		9.2	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. Essentially independent of operating temperature typical characteristics.

#### **TYPICAL PERFORMANCE CHARACTERISTICS**

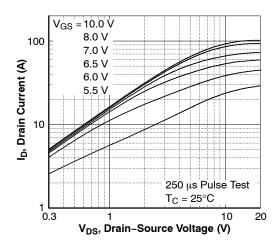
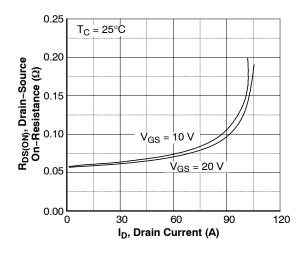
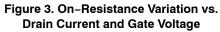


Figure 1. On–Region Characteristics





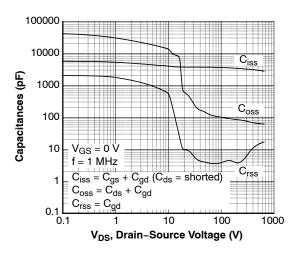


Figure 5. Capacitance Characteristics

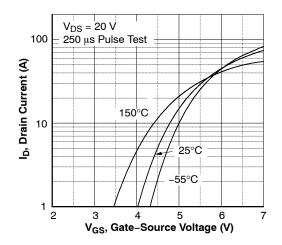
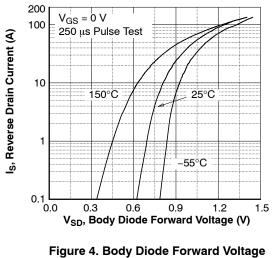


Figure 2. Transfer Characteristics



Igure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

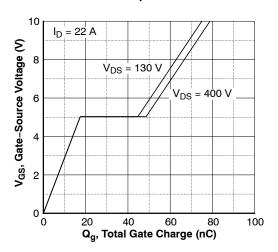


Figure 6. Gate Charge Characteristics

#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)

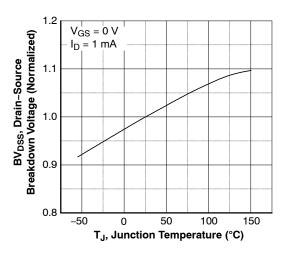


Figure 7. Breakdown Voltage Variation vs. Temperature

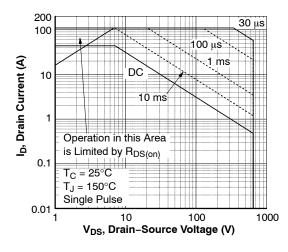


Figure 9. Maximum Safe Operating Area

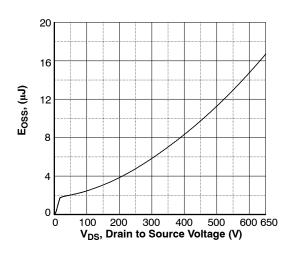


Figure 11. E<sub>OSS</sub> vs. Drain to Source Voltage

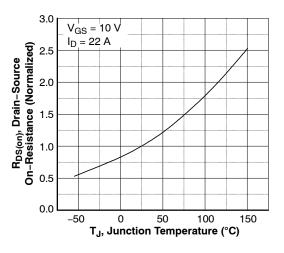


Figure 8. On–Resistance Variation vs. Temperature

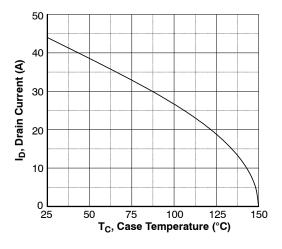


Figure 10. Maximum Drain Current vs. Case Temperature

### TYPICAL PERFORMANCE CHARACTERISTICS (continued)

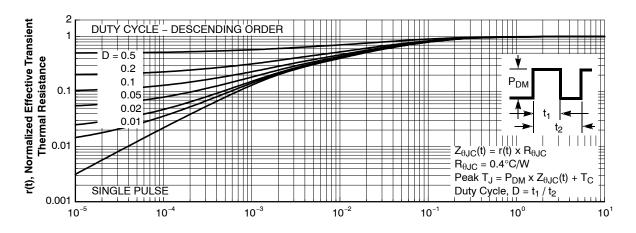
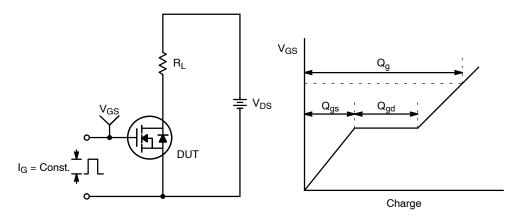


Figure 12. Transient Thermal Response Curve





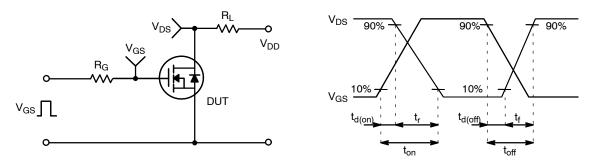
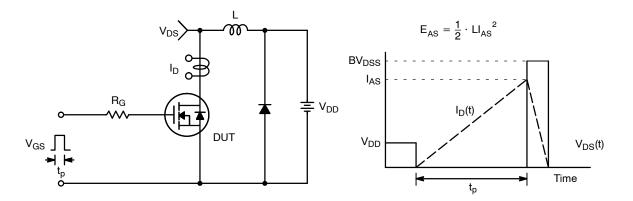


Figure 14. Resistive Switching Test Circuit & Waveforms





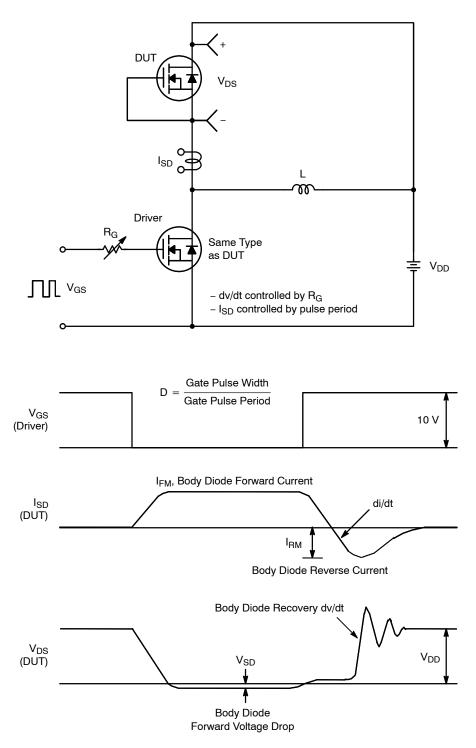
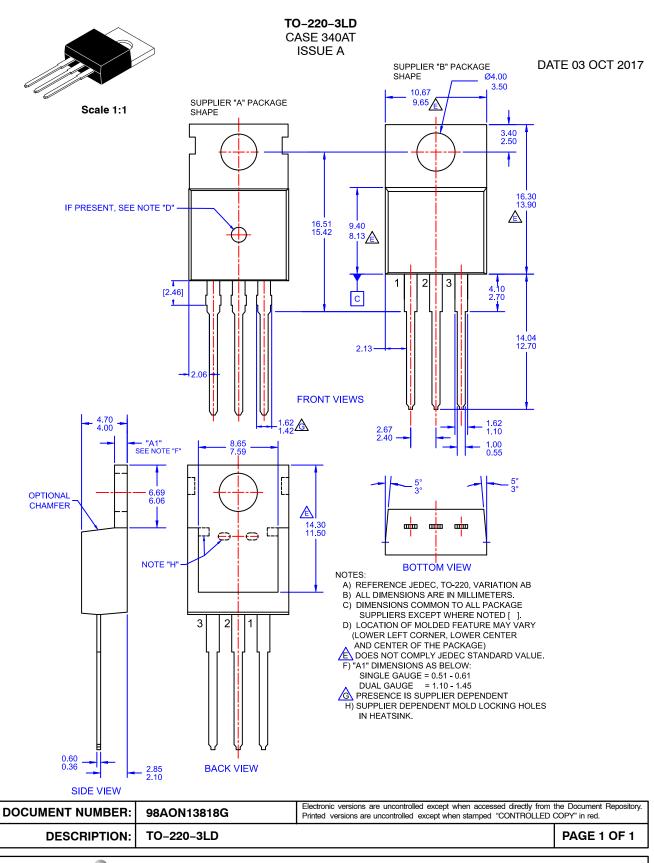


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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